


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Roy Knechtel et al.  
Serial No. : 10/580,361  
International Application No. : PCT/DE2004/002638  
Filed :  
International Filing Date : 11/29/2004  
Title : PRODUCTION OF SEMICONDUCTOR SUBSTRATES  
WITH BURIED LAYERS BY JOINING (BONDING)  
SEMICONDUCTOR WAFERS  
Attorney Docket : LEO 003 PA  
Examiner :  
Art Unit : CERTIFICATE OF MAILING

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Attorney Reg. No. 28,046

Sir:

**PRELIMINARY AMENDMENT**

Please preliminary amend the present application, which is the National Stage  
entry in the United States of PCT/DE2004/002638, prior to calculation of the filing fee.  
Please amend the application as follows.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims, which begins  
on page 4 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.